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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Product Status	Discontinued at Digi-Key
Core Processor	M8C
Core Size	8-Bit
Speed	24MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	28
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	A/D 28x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c21434-24ltxias



PSoC Functional Overview

The PSoC family consists of many devices with on-chip controllers. These devices are designed to replace multiple traditional MCU-based system components with one low-cost single-chip programmable component. A PSoC device includes configurable blocks of analog and digital logic, and programmable interconnect. This architecture makes it possible for you to create customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast central processing unit (CPU), flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The PSoC architecture, shown in Figure 2, consists of four main areas: the core, the system resources, the digital system, and the analog system. Configurable global bus resources allow combining all of the device resources into a complete custom system. Each CY8C21x34 PSoC device includes four digital blocks and four analog blocks. Depending on the PSoC package, up to 28 GPIOs are also included. The GPIOs provide access to the global digital and analog interconnects.

The PSoC Core

The PSoC core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, and internal main oscillator (IMO) and internal low speed oscillator (ILO). The CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz $^{\left[3\right]}$. The M8C is a four-million instructions per second (MIPS) 8-bit Harvard-architecture microprocessor.

System resources provide these additional capabilities:

- Digital clocks for increased flexibility
- I²C [4] functionality to implement an I²C master and slave
- An internal voltage reference, multi-master, that provides an absolute value of 1.3 V to a number of PSoC subsystems
- A SMP that generates normal operating voltages from a single battery cell
- Various system resets supported by the M8C

The digital system consists of an array of digital PSoC blocks that may be configured into any number of digital peripherals. The digital blocks are connected to the GPIOs through a series of global buses. These buses can route any signal to any pin, freeing designs from the constraints of a fixed peripheral controller.

The analog system consists of four analog PSoC blocks, supporting comparators, and analog-to-digital conversion up to 10 bits of precision.

The Digital System

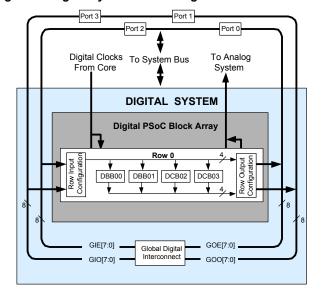
The digital system consists of four digital PSoC blocks. Each block is an 8-bit resource that is used alone or combined with other blocks to form 8-, 16-, 24-, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include:

- PWMs (8- to 32-bit)
- PWMs with dead band (8- to 32-bit)
- Counters (8- to 32-bit)
- Timers (8- to 32-bit)
- UART 8- with selectable parity
- Serial peripheral interface (SPI) master and slave
- I²C slave and multi-master [4]
- CRC/generator (8-bit)
- IrDA
- PRS generators (8-bit to 32-bit)

The digital blocks are connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 6.

Figure 2. Digital System Block Diagram



Notes

- 3. Errata: The worst case IMO frequency deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.
- Errata: The I²C block exhibits occasional data and bus corruption errors when the I²C master initiates transactions while the device is transitioning in to or out of sleep mode.



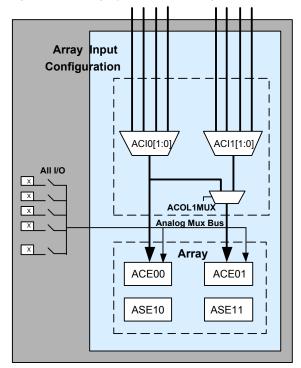
The Analog System

The analog system consists of four configurable blocks that allow for the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the common PSoC analog functions for this device (most available as user modules) are:

- ADCs (single or dual, with 8-bit or 10-bit resolution)
- Pin-to-pin comparator
- Single-ended comparators (up to two) with absolute (1.3 V) reference or 8-bit DAC reference
- 1.3-V reference (as a system resource)

In most PSoC devices, analog blocks are provided in columns of three, which includes one continuous time (CT) and two switched capacitor (SC) blocks. The CY8C21x34 devices provide limited functionality Type E analog blocks. Each column contains one CT Type E block and one SC Type E block. Refer to the *PSoC Technical Reference Manual* for detailed information on the CY8C21x34's Type E analog blocks.

Figure 3. Analog System Block Diagram



The Analog Multiplexer System

The analog mux bus can connect to every GPIO pin. Pins may be connected to the bus individually or in any combination. The bus also connects to the analog system for analysis with comparators and analog-to-digital converters. An additional 8:1 analog input multiplexer provides a second path to bring Port 0 pins to the analog array.

Switch-control logic enables selected pins to precharge continuously under hardware control. This enables capacitive measurement for applications such as touch sensing. Other multiplexer applications include:

- Track pad, finger sensing
- Chip-wide mux that allows analog input from any I/O pin
- Crosspoint connection between any I/O pin combinations

Additional System Resources

System resources, some of which are listed in the previous sections, provide additional capability useful to complete systems. Additional resources include a switch-mode pump, low-voltage detection, and power-on-reset (POR).

- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks may be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.
- The I²C ^[5] module provides 100- and 400-kHz communication over two wires. Slave, master, and multi-master modes are all supported.
- LVD interrupts can signal the application of falling voltage levels, while the advanced POR circuit eliminates the need for a system supervisor.
- An internal 1.3-V reference provides an absolute reference for the analog system, including ADCs and DACs.
- An integrated switch-mode pump generates normal operating voltages from a single 1.2-V battery cell, providing a low cost boost converter.
- Versatile analog multiplexer system.

Note

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^{5.} Errata:The I²C block exhibits occasional data and bus corruption errors when the I2C master initiates transactions while the device is transitioning in to or out of sleep mode.



Development Tools

PSoC Designer™ is the revolutionary integrated design environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
 - ☐ Hardware and software I²C [8] slaves and masters
 - □ Full-speed USB 2.0
 - □ Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are ADCs, DACs, amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this allows you to use more than 100 percent of PSoC's resources for an application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and are linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows you to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an online support Forum to aid the designer.

In-Circuit Emulator

A low-cost, high-functionality in-circuit emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24 MHz) operation.

Note

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^{8.} Errata:The I²C block exhibits occasional data and bus corruption errors when the I²C master initiates transactions while the device is transitioning in to or out of sleep mode.

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56-pin Part Pinout

The 56-pin SSOP part is for the CY8C21001 on-chip debug (OCD) PSoC device.

Note This part is only used for in-circuit debugging. It is NOT available for production.

Vss AI, P0[7] AI, P0[5] 53 AI, P0[3] AI, P0[1] P2[7] P2[5] P2[3] = P2[1] = NC = 48 NC = OCDE = **SSOP** OCDO = 15 SMP = 16 Vss 🚽 Vss Vss P3[3] P3[1] NC NC P1[2C SCL, P1[7] P12C SDA, P1[5] P15] P15] 38 37 34 32 P1[3] = SCLK, I2C SCL, P1[1] = Vss 30 Vss

Figure 10. CY8C21001 56-pin PSoC Device

CY8C21001 56-pin SSOP Pin Definitions

Pin No.	Ту	Туре		Description
FIII NO.	Digital	Analog	Pin Name	Description
1	Power	•	V_{SS}	Ground connection [18]
2	I/O	I	P0[7]	Analog column mux input
3	I/O	İ	P0[5]	Analog column mux input and column output
4	I/O	I	P0[3]	Analog column mux input and column output
5	I/O	I	P0[1]	Analog column mux input
6	I/O		P2[7]	
7	I/O		P2[5]	
8	I/O	I	P2[3]	Direct switched capacitor block input
9	I/O	I	P2[1]	Direct switched capacitor block input
10			NC	No connection. Pin must be left floating
11			NC	No connection. Pin must be left floating
12			NC	No connection. Pin must be left floating
13			NC	No connection. Pin must be left floating
14	OCD		OCDE	OCD even data I/O
15	OCD		OCDO	OCD odd data output
16	Power	•	SMP	SMP connection to required external components
17	Power		V_{SS}	Ground connection [18]
18	Power		V_{SS}	Ground connection [18]
19	I/O		P3[3]	

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CY8C21001 56-pin SSOP Pin Definitions (continued)

- :	Ту	ре		Description					
Pin No.	Digital	Analog	Pin Name						
20	I/O		P3[1]						
21		- V	NC	No connection. Pin must be left floating					
22			NC	No connection. Pin must be left floating					
23	I/O		P1[7]	I ² C SCL					
24	I/O		P1[5]	I ² C SDA					
25		·!	NC	No connection. Pin must be left floating					
26	I/O		P1[3]	I _{FMTEST}					
27	I/O		P1[1]	I ² C SCL, ISSP-SCLK ^[19]					
28	Power	•	V _{SS}	Ground connection [18]					
29			NC	No connection. Pin must be left floating					
30			NC	No connection. Pin must be left floating					
31	I/O		P1[0]	I ² C SDA, ISSP-SDATA ^[19]					
32	I/O		P1[2]	V _{FMTEST}					
33	I/O		P1[4]	Optional external clock input (EXTCLK)					
34	I/O		P1[6]						
35		- V	NC	No connection. Pin must be left floating					
36			NC	No connection. Pin must be left floating					
37			NC	No connection. Pin must be left floating					
38			NC	No connection. Pin must be left floating					
39			NC	No connection. Pin must be left floating					
40			NC	No connection. Pin must be left floating					
41	Input		XRES	Active high external reset with internal pull-down					
42	OCD		HCLK	OCD high-speed clock output					
43	OCD		CCLK	OCD CPU clock output					
44	I/O		P3[0]						
45	I/O		P3[2]						
46		•	NC	No connection. Pin must be left floating					
47			NC	No connection. Pin must be left floating					
48	I/O	I	P2[0]						
49	I/O	I	P2[2]						
50	I/O		P2[4]						
51	I/O		P2[6]						
52	I/O	I	P0[0]	Analog column mux input					
53	I/O	I	P0[2]	Analog column mux input and column output					
54	I/O	I	P0[4]	Analog column mux input and column output					
55	I/O	I	P0[6]	Analog column mux input					
56	Power		V_{DD}	Supply voltage					

LEGEND: A = Analog, I = Input, O = Output, and OCD = On-Chip Debug.

Notes

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^{18.} All V_{SS} pins should be brought out to one common GND plane.
19. These are the ISSP pins, which are not High Z at POR. See the *PSoC Technical Reference Manual* for details.



Register Reference

This chapter lists the registers of the CY8C21x34 PSoC device. For detailed register information, see the *PSoC Technical Reference Manual*.

Register Conventions

The register conventions specific to this section are listed in Table 2.

Table 2. Register Conventions

Convention	Description						
R	Read register or bit(s)						
W	Write register or bit(s)						
L	Logical register or bit(s)						
С	Clearable register or bit(s)						
#	Access is bit specific						

Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks, Bank 0 and Bank 1. The XOI bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XOI bit is set to 1, the user is in Bank 1.

Note In the following register mapping tables, blank fields are reserved and must not be accessed.

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Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8C21x34 PSoC device. For up-to-date electrical specifications, visit the Cypress web site at http://www.cypress.com.

Specifications are valid for $-40~^{\circ}\text{C} \le T_A \le 85~^{\circ}\text{C}$ and $T_{.1} \le 100~^{\circ}\text{C}$ as specified, except where noted.

Refer to Table 16 on page 26 for the electrical specifications for the IMO using SLIMO mode.

Figure 11. Voltage versus CPU Frequency

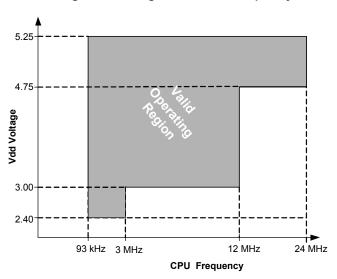
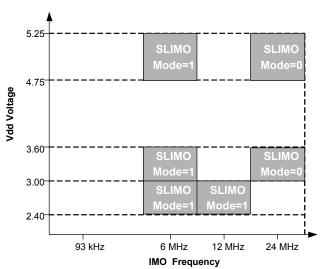


Figure 14. IMO Frequency Trim Options



DC Electrical Characteristics

DC Chip-Level Specifications

Table 5 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, 3.0 V to 3.6 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, or 2.4 V to 3.0 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 5. DC Chip-level Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V_{DD}	Supply voltage	2.40	-	5.25	V	See Table 13 on page 24
I _{DD}	Supply current, IMO = 24 MHz	-	3	4	mA	Conditions are V_{DD} = 5.0 V, T_A = 25 °C, CPU = 3 MHz, 48 MHz disabled. VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz
I _{DD3}	Supply current, IMO = 6 MHz using SLIMO mode.	-	1.2	2	mA	Conditions are V_{DD} = 3.3 V, T_A = 25 °C, CPU = 3 MHz, clock doubler disabled. VC1 = 375 kHz, VC2 = 23.4 kHz, VC3 = 0.091 kHz
I _{DD27}	Supply current, IMO = 6 MHz using SLIMO mode.	-	1.1	1.5	mA	Conditions are V_{DD} = 2.55 V, T_A = 25 °C, CPU = 3 MHz, clock doubler disabled. VC1 = 375 kHz, VC2 = 23.4 kHz, VC3 = 0.091 kHz
I _{SB27}	Sleep (mode) current with POR, LVD, sleep timer, WDT, and internal slow oscillator active. Mid temperature range.	_	2.6	4	□µA	V_{DD} = 2.55 V, 0 °C ≤ T_A ≤ 40 °C
I _{SB}	Sleep (mode) current with POR, LVD, Sleep Timer, WDT, and internal slow oscillator active.	_	2.8	5	μA	V_{DD} = 3.3 V, -40 °C \leq T _A \leq 85 °C
V_{REF}	Reference voltage (Bandgap)	1.28	1.30	1.32	V	Trimmed for appropriate V_{DD} V_{DD} = 3.0 V to 5.25 V
V _{REF27}	Reference voltage (Bandgap)	1.16	1.30	1.33	V	Trimmed for appropriate V _{DD} V _{DD} = 2.4 V to 3.0 V
AGND	Analog ground	$V_{REF} - 0.003$	V_{REF}	V _{REF} + 0.003	V	

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DC Operational Amplifier Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, or 2.4 V to 3.0 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 8. 5-V DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V_{OSOA}	Input offset voltage (absolute value)	_	2.5	15	mV	
TCV _{OSOA}	Average input offset voltage drift	_	10	_	μV/°C	
I _{EBOA}	Input leakage current (Port 0 analog pins 7-to-1)	_	200	_	pА	Gross tested to 1 μA
I _{EBOA00}	Input leakage current (Port 0, Pin 0 analog pin)	_	50	_	nA	Gross tested to 1 μA
C _{INOA}	Input capacitance (Port 0 analog pins)	-	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V_{CMOA}	Common mode voltage range	0.0	-	V _{DD} – 1.0	V	
G _{OLOA}	Open loop gain	=	80	_	dB	
I _{SOA}	Amplifier supply current	1	10	30	μΑ	

Table 9. 3.3-V DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{OSOA}	Input offset voltage (absolute value)	_	2.5	15	mV	
TCV _{OSOA}	Average input offset voltage drift	_	10	-	μV/°C	
I _{EBOA}	Input leakage current (Port 0 analog pins)	_	200	-	pА	Gross tested to 1 μA
I _{EBOA00}	Input leakage current (Port 0, Pin 0 analog pin)	_	50	-	nA	Gross tested to 1 μA
C _{INOA}	Input capacitance (Port 0 analog pins)	_	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V_{CMOA}	Common mode voltage range	0	_	V _{DD} – 1.0	V	
G _{OLOA}	Open loop gain	_	80	_	dB	
I _{SOA}	Amplifier supply current	_	10	30	μA	

Table 10. 2.7-V DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{OSOA}	Input offset voltage (absolute value)	-	2.5	15	mV	
TCV _{OSOA}	Average input offset voltage drift	-	10	-	μV/°C	
I _{EBOA}	Input leakage current (Port 0 analog pins)	-	200	-	pА	Gross tested to 1 μA
I _{EBOA00}	Input leakage current (Port 0, Pin 0 analog pin)	-	50	-	nA	Gross tested to 1 μA
C _{INOA}	Input capacitance (Port 0 analog pins)	-	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V _{CMOA}	Common mode voltage range	0	_	V _{DD} – 1.0	V	
G _{OLOA}	Open loop gain	_	80	_	dB	
I _{SOA}	Amplifier supply current	_	10	30	μA	

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AC Digital Block Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, or 2.4 V to 3.0 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 21. 5-V and 3.3-V AC Digital Block Specifications

Function	Description	Min	Тур	Max	Unit	Notes
All functions	Block input clock frequency	ı				
	V _{DD} ≥ 4.75 V	_	_	49.2	MHz	
	V _{DD} < 4.75 V	_	_	24.6	MHz	
Timer	Input clock frequency	I.	l	I.	u .	
	No capture, V _{DD} ≥ 4.75 V	_	_	49.2	MHz	
	No capture, V _{DD} < 4.75 V	_	_	24.6	MHz	
	With capture	_	_	24.6	MHz	
	Capture pulse width	50 ^[37]	_	_	ns	
Counter	Input clock frequency				•	
	No enable input, V _{DD} ≥ 4.75 V	_	_	49.2	MHz	
	No enable input, V _{DD} < 4.75 V	_	_	24.6	MHz	
	With enable input	_	_	24.6	MHz	
	Enable input pulse width	50 ^[37]	_	_	ns	
Dead Band	Kill pulse width	•		•		
	Asynchronous restart mode	20	-	_	ns	
	Synchronous restart mode	50 ^[37]	_	-	ns	
	Disable mode	50 ^[37]	_	-	ns	
	Input clock frequency					
	V _{DD} ≥ 4.75 V	_	_	49.2	MHz	
	V _{DD} < 4.75 V	_	_	24.6	MHz	
CRCPRS	Input clock frequency					
(PRS Mode)	V _{DD} ≥ 4.75 V	_	_	49.2	MHz	
	V _{DD} < 4.75 V	_	_	24.6	MHz	
CRCPRS (CRC Mode)	Input clock frequency	_	-	24.6	MHz	
SPIM	Input clock frequency	_	-	8.2	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock (SCLK) frequency	_	-	4.1	MHz	The input clock is the SPI SCLK in SPIS mode.
	Width of SS_negated between transmissions	50 ^[37]	-	_	ns	
Transmitter	Input clock frequency					The baud rate is equal to the input clock frequency
	$V_{DD} \ge 4.75 \text{ V}, 2 \text{ stop bits}$	_	_	49.2	MHz	divided by 8.
	$V_{DD} \ge 4.75 \text{ V}, 1 \text{ stop bit}$	_	_	24.6	MHz	
	V _{DD} < 4.75 V	_	-	24.6	MHz	
Receiver	Input clock frequency					The baud rate is equal to the input clock frequency divided by 8.
	$V_{DD} \ge 4.75 \text{ V}, 2 \text{ stop bits}$	_	_	49.2	MHz	
	$V_{DD} \ge 4.75 \text{ V}, 1 \text{ stop bit}$	_	_	24.6	MHz	
	V _{DD} < 4.75 V	_	_	24.6	MHz	

Note

37.50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

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Table 22. 2.7-V AC Digital Block Specifications

Function	Description	Min	Тур	Max	Units	Notes
All functions	Block input clock frequency	-	-	12.7	MHz	2.4 V < V _{DD} < 3.0 V
Timer	Capture pulse width	100 ^[38]	_	_	ns	
	Input clock frequency, with or without capture	-	-	12.7	MHz	
Counter	Enable input pulse width	100	-	_	ns	
	Input clock frequency, no enable input	-	-	12.7	MHz	
	Input clock frequency, enable input	-	-	12.7	MHz	
Dead Band	Kill pulse width:					
	Asynchronous restart mode	20	_	_	ns	
	Synchronous restart mode	100	_	_	ns	
	Disable mode	100	_	_	ns	
	Input clock frequency	_	_	12.7	MHz	
CRCPRS (PRS Mode)	Input clock frequency	_	-	12.7	MHz	
CRCPRS (CRC Mode)	Input clock frequency	_	_	12.7	MHz	
SPIM	Input clock frequency	-	-	6.35	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock (SCLK) frequency	_	_	4.1	MHz	
	Width of SS_ Negated between transmissions	100	-	_	ns	
Transmitter	Input clock frequency	_	-	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.
Receiver	Input clock frequency	-	-	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.

AC External Clock Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, or 3.0 V to 3.6 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 23. 5-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
F _{OSCEXT}	Frequency	0.093	_	24.6	MHz	
_	High period	20.6	_	5300	ns	
_	Low period	20.6	_	-	ns	
_	Power-up IMO to switch	150	-	-	μs	

Note

38. 100 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

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Table 24. 3.3-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
F _{OSCEXT}	Frequency with CPU clock divide by 1	0.093	_	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.186	-	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met
_	High period with CPU clock divide by 1	41.7	_	5300	ns	
_	Low period with CPU clock divide by 1	41.7	-	-	ns	
_	Power-up IMO to switch	150	_	_	μs	

Table 25. 2.7-V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
F _{OSCEXT}	Frequency with CPU clock divide by 1	0.093	_	3.08	MHz	Maximum CPU frequency is 3 MHz at 2.7 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.186	-	6.35	MHz	If the frequency of the external clock is greater than 3 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met
_	High period with CPU clock divide by 1	160	_	5300	ns	
_	Low period with CPU clock divide by 1	160	_	_	ns	
_	Power-up IMO to switch	150	_	_	μs	

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AC Programming Specifications

Table 26 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40 \text{ °C} \leq T_A \leq 85 \text{ °C}$, or 3.0 V to 3.6 V and $-40 \text{ °C} \leq T_A \leq 85 \text{ °C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 26. AC Programming Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{RSCLK}	Rise time of SCLK	1	_	20	ns	
T _{FSCLK}	Fall time of SCLK	1	_	20	ns	
T _{SSCLK}	Data setup time to falling edge of SCLK	40	_	_	ns	
T _{HSCLK}	Data hold time from falling edge of SCLK	40	-	_	ns	
F _{SCLK}	Frequency of SCLK	0	-	8	MHz	
T _{ERASEB}	Flash erase time (block)	_	10	_	ms	
T _{WRITE}	Flash block write time	_	40	_	ms	
T _{DSCLK}	Data out delay from falling edge of SCLK	_	_	45	ns	3.6 < V _{DD}
T _{DSCLK3}	Data out delay from falling edge of SCLK	_	-	50	ns	$3.0 \leq V_{DD} \leq 3.6$
T _{DSCLK2}	Data out delay from falling edge of SCLK	_	_	70	ns	$2.4 \leq V_{DD} \leq 3.0$
T _{ERASEALL}	Flash erase time (Bulk)	_	20	_	ms	Erase all blocks and protection fields at once
T _{PROGRAM_HOT}	Flash block erase + flash block write time	_	_	100 ^[39]	ms	0 °C ≤ Tj ≤ 100 °C
T _{PROGRAM_COLD}	Flash block erase + flash block write time	-	_	200 ^[39]	ms	-40 °C ≤ Tj ≤ 0 °C

AC I²C [40] Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, or 2.4 V to 3.0 V and $-40~^{\circ}\text{C} \le T_{A} \le 85~^{\circ}\text{C}$, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 $^{\circ}\text{C}$ and are for design guidance only.

Table 27. AC Characteristics of the I^2C SDA and SCL Pins for $V_{DD} \ge 3.0 \text{ V}$

Cumbal	Description	Standa	rd Mode	Fast M	Heite	
Symbol	Description	Min	Max	Min	Max	Units
F _{SCLI2C}	SCL clock frequency	0	100	0	400	kHz
T _{HDSTAI2C}	Hold time (repeated) start condition. After this period, the first clock pulse is generated	4.0	_	0.6	_	μs
T _{LOWI2C}	Low period of the SCL clock	4.7	_	1.3	_	μs
T _{HIGHI2C}	High period of the SCL clock	4.0	_	0.6	_	μs
T _{SUSTAI2C}	Setup time for a repeated start condition	4.7	_	0.6	-	μs
T _{HDDATI2C}	Data hold time	0	_	0	_	μs
T _{SUDATI2C}	Data setup time	250	_	100 ^[41]	_	ns
T _{SUSTOI2C}	Setup time for stop condition	4.0	_	0.6	_	μs
T _{BUFI2C}	Bus free time between a stop and start condition	4.7	-	1.3	_	μs
T _{SPI2C}	Pulse width of spikes suppressed by the input filter.	_	-	0	50	ns

Note

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^{39.} For the full industrial range, the user must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs application note AN2015 (Design Aids - Reading and Writing PSoC® Flash) for more information.

^{40.} Errata: The I²C block exhibits occasional data and bus corruption errors when the I²C master initiates transactions while the device is transitioning in to or out of sleep mode.

^{41.} A Fast-Mode I²C-bus device may be used in a Standard-Mode I²C-bus system, but it must meet the requirement T_{SU;DAT} ≥ 250 ns. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If the device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line T_{rmax} + T_{SU;DAT} = 1000 + 250 = 1250 ns (according to the Standard-Mode I²C-bus specification) before the SCL line is released.



Thermal Impedances

Table 29. Thermal Impedances per Package

Package	Typical θ _{JA} ^[42]	Typical θ _{JC}
16-pin SOIC	123 °C/W	55 °C/W
20-pin SSOP	117 °C/W	41 °C/W
28-pin SSOP	96 °C/W	39 °C/W
32-pin QFN ^[43] 5 × 5 mm 0.60 Max	27 °C/W	15 °C/W
32-pin QFN ^[43] 5 × 5 mm 1.00 Max	22 °C/W	12 °C/W
56-pin SSOP	48 °C/W	24 °C/W

Solder Reflow Specifications

Table 30 shows the solder reflow temperature limits that must not be exceeded.

Table 30. Solder Reflow Specifications

Package	Maximum Peak Temperature (T _C)	Maximum Time above T _C – 5 °C		
16-pin SOIC	260 °C	30 seconds		
20-pin SSOP	260 °C	30 seconds		
28-pin SSOP	260 °C	30 seconds		
32-pin QFN	260 °C	30 seconds		
56-pin SSOP	260 °C	30 seconds		

Notes

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 ^{42.} T_J = T_A + Power × θ_{JA}
 43. To achieve the thermal impedance specified for the QFN package, refer to Application Note EROS - Design Guidelines for Cypress Quad Flat No Extended Lead (QFN) Packaged Devices available at http://www.cypress.com.

^{44.} Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are 220 ± 5 °C with Sn-Pb or 245 ± 5 °C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.



Development Tool Selection

This section presents the development tools available for all current PSoC device families including the CY8C21x34 family.

Software

PSoC Designer™

At the core of the PSoC development software suite is PSoC Designer, used to generate PSoC firmware applications. PSoC Designer is available free of charge at http://www.cypress.com and includes a free C compiler.

PSoC Programmer

Flexible enough to be used on the bench in development, yet suitable for factory programming, PSoC Programmer works either as a standalone programming application or operates directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE-Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at http://www.cypress.com.

Development Kits

All development kits can be purchased from the Cypress Online Store.

CY3215-DK Basic Development Kit

The CY3215-DK is for prototyping and development with PSoC Designer. This kit supports in-circuit emulation, and the software interface allows you to run, halt, and single step the processor, and view the content of specific memory locations. Advance emulation features also supported through PSoC Designer. The kit includes:

- PSoC Designer software CD
- ICE-Cube in-circuit emulator
- ICE Flex-Pod for CY8C29x66 family
- Cat-5 adapter
- Mini-Eval programming board
- 110 ~ 240 V power supply, Euro-Plug adapter
- iMAGEcraft C compiler
- ISSP cable
- USB 2.0 cable and Blue Cat-5 cable
- Two CY8C29466-24PXI 28-PDIP chip samples

Evaluation Tools

All evaluation tools can be purchased from the Cypress Online Store

CY3210-MiniProg1

The CY3210-MiniProg1 kit allows you to program PSoC devices through the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC through a provided USB 2.0 cable. The kit includes:

- MiniProg programming unit
- MiniEval socket programming and evaluation board
- 28-pin CY8C29466-24PXI PDIP PSoC device sample
- 28-pin CY8C27443-24PXI PDIP PSoC device sample
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3210-PSoCEval1

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- Evaluation board with LCD module
- MiniProg programming unit
- Two 28-pin CY8C29466-24PXI PDIP PSoC device samples
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3214-PSoCEvalUSB

The CY3214-PSoCEvalUSB evaluation kit features a development board for the CY8C24794-24LFXI PSoC device. The board includes both USB and capacitive sensing development and debugging support. This evaluation board also includes an LCD module, potentiometer, LEDs, an enunciator and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- PSoCEvalUSB board
- LCD module
- MIniProg programming unit
- Mini USB cable
- PSoC Designer and example projects CD
- Getting Started guide
- Wire pack



Glossary (continued)

bias

- 1. A systematic deviation of a value from a reference value.
- The amount by which the average of a set of values departs from a reference value.
- 3. The electrical, mechanical, magnetic, or other force (field) applied to a device to establish a reference level to operate the device.

block

- 1. A functional unit that performs a single function, such as an oscillator.
- A functional unit that may be configured to perform one of several functions, such as a digital PSoC block or an analog PSoC block.

buffer

- 1. A storage area for data that is used to compensate for a speed difference, when transferring data from one device to another. Usually refers to an area reserved for IO operations, into which data is read, or from which data is written.
- 2. A portion of memory set aside to store data, often before it is sent to an external device or as it is received from an external device.
- 3. An amplifier used to lower the output impedance of a system.

bus

- 1. A named connection of nets. Bundling nets together in a bus makes it easier to route nets with similar routing patterns.
- 2. A set of signals performing a common function and carrying similar data. Typically represented using vector notation; for example, address[7:0].
- 3. One or more conductors that serve as a common connection for a group of related devices.

clock

The device that generates a periodic signal with a fixed frequency and duty cycle. A clock is sometimes used to synchronize different logic blocks.

comparator

An electronic circuit that produces an output voltage or current whenever two input levels simultaneously satisfy predetermined amplitude requirements.

compiler

A program that translates a high level language, such as C, into machine language.

configuration space

In PSoC devices, the register space accessed when the XIO bit, in the CPU F register, is set to '1'.

crystal oscillator

An oscillator in which the frequency is controlled by a piezoelectric crystal. Typically a piezoelectric crystal is less sensitive to ambient temperature than other circuit components.

check (CRC)

cyclic redundancy A calculation used to detect errors in data communications, typically performed using a linear feedback shift register. Similar calculations may be used for a variety of other purposes such as data compression.

data bus

A bi-directional set of signals used by a computer to convey information from a memory location to the central processing unit and vice versa. More generally, a set of signals used to convey data between digital functions.

debugger

A hardware and software system that allows you to analyze the operation of the system under development. A debugger usually allows the developer to step through the firmware one step at a time, set break points, and analyze memory.

dead band

A period of time when neither of two or more signals are in their active state or in transition.

digital blocks

The 8-bit logic blocks that can act as a counter, timer, serial receiver, serial transmitter, CRC generator, pseudo-random number generator, or SPI.

digital-to-analog (DAC)

A device that changes a digital signal to an analog signal of corresponding magnitude. The analog-to-digital (ADC) converter performs the reverse operation.

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Glossary (continued)

microcontroller An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a

microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for

general-purpose computation as is a microprocessor.

mixed-signal The reference to a circuit containing both analog and digital techniques and components.

modulator A device that imposes a signal on a carrier.

noise 1. A disturbance that affects a signal and that may distort the information carried by the signal.

2. The random variations of one or more characteristics of any entity such as voltage, current, or data.

oscillator A circuit that may be crystal controlled and is used to generate a clock frequency.

parity A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the

digits of the binary data either always even (even parity) or always odd (odd parity).

Phase-locked An electronic circuit that controls an **oscillator** so that it maintains a constant phase angle relative to a reference loop (PLL) signal.

pinouts The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their

physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between

schematic and PCB design (both being computer generated files) and may also involve pin names.

port A group of pins, usually eight.

Power on reset A circuit that forces the PSoC device to reset when the voltage is below a pre-set level. This is one type of hardware

Power on reset (POR)

reset.

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of Cypress.

PSoC Designer™ The software for Cypress' Programmable System-on-Chip technology.

pulse width modulator (PWM)

An output in the form of duty cycle which varies as a function of the applied measurand

RAM An acronym for random access memory. A data-storage device from which data can be read out and new data

can be written in.

register A storage device with a specific capacity, such as a bit or byte.

reset A means of bringing a system back to a know state. See hardware reset and software reset.

ROM An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot

be written in.

serial 1. Pertaining to a process in which all events occur one after the other.

2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or

channel.

settling time The time it takes for an output signal or value to stabilize after the input has changed from one value to another.

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Errata

This section describes the errata for the $PSoC^{\circledR}$ Programmable System-on-Chip CY8C21X34. Details include errata trigger conditions, scope of impact, available workarounds, and silicon revision applicability.

Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Ordering Information
CY8C21X34	CY8C21234-24SXI
	CY8C21234-24SXIT
	CY8C21334-24PVXI
	CY8C21334-24PVXIT
	CY8C21534-24PVXI
	CY8C21534-24PVXIT
	CY8C21434-24LFXI
	CY8C21434-24LFXIT
	CY8C21434-24LKXI
	CY8C21434-24LKXIT
	CY8C21634-24LFXI
	CY8C21634-24LFXIT
	CY8C21434-24LTXI
	CY8C21434-24LTXIT
	CY8C21434-24LQXI
	CY8C21434-24LQXIT
	CY8C21634-24LTXI
	CY8C21634-24LTXIT
	CY8C21001-24PVXI

CY8C21X34 Qualification Status

Product Status: Production



CY8C21X34 Errata Summary

The following table defines the errata applicability to available CY8C21X34 family devices. An "X" indicates that the errata pertains to the selected device.

Note Errata items, in the table below, are hyperlinked. Click on any item entry to jump to its description.

Items	Part Number	Silicon Revision	Fix Status
[1.]. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes	CY8C21X34	А	No fix is currently planned.
[2]. I2C Errors	CY8C21X34	Α	No fix is currently planned.

1. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes

■ Problem Definition

Asynchronous Digital Communications Interfaces may fail framing beyond 0 $^{\circ}$ C to 70 $^{\circ}$ C. This problem does not affect end-product usage between 0 $^{\circ}$ C and 70 $^{\circ}$ C.

■ Parameters Affected

The IMO frequency tolerance. The worst case deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.

■ Trigger Condition(S)

The asynchronous Rx/Tx clock source IMO frequency tolerance may deviate beyond the datasheet limit of $\pm 2.5\%$ when operated beyond the temperature range of 0 °C to ± 70 °C.

■ Scope of Impact

This problem may affect UART, IrDA, and FSK implementations.

■ Workaround

Implement a quartz crystal stabilized clock source on at least one end of the asynchronous digital communications interface.

■ Fix Status

No fix is currently planned.

2. I²C Errors

■ Problem Definition

The I²C block exhibits occasional data and bus corruption errors when the I²C master initiates transactions while the device is transitioning in to or out of sleep mode.

■ Parameters Affected

Affects reliability of I²C communication to device, between I²C master, and third party I²C slaves.

■ Trigger Condition(S)

Triggered by transitions into and out of the device's sleep mode.

■ Scope of Impact

This problem may affect UART, IrDA, and FSK implementations.

■ Workaround

Firmware workarounds are available in firmware. Generally the workaround consists of disconnecting the I^2C block from the bus prior to going to sleep modes. I^2C transactions during sleep are supported by a protocol in which the master wakes the device prior to the I^2C transaction

■ Fix Status

Will not be fixed.

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Document History Page

Rev.	ECN	Orig. of Change	Submission Date	Description of Change	
**	227340	HMT	See ECN	New silicon and document (Revision **).	
*A	235992	SFV	See ECN	Updated Overview and Electrical Spec. chapters, along with revisions to the 24-Pin pinout part. Revised the register mapping tables. Added a SSOP 28-Pir part.	
*B	248572	SFV	See ECN	Changed title to include all part #s. Changed 28-Pin SSOP from CY8C21434 to CY8C21534. Changed pin 9 on the 28-Pin SSOP from SMP pin to Vss pin. Added SMP block to architecture diagram. Update Electrical Specifications. Added another 32-Pin MLF part: CY8C21634.	
*C	277832	НМТ	See ECN	Verify datasheet standards from SFV memo. Add Analog Input Mux to applicable pin outs. Update PSoC Characteristics table. Update diagrams and specs. Final.	
*D	285293	HMT	See ECN	Update 2.7 V DC GPIO spec. Add Reflow Peak Temp. table.	
*E	301739	HMT	See ECN	DC Chip-Level Specification changes. Update links to new CY.com Portal.	
*F	329104	HMT	See ECN	Re-add pinout ISSP notation. Fix TMP register names. Clarify ADC for Update Electrical Specifications. Update Reflow Peak Temp. table. At MLF E-PAD dimensions. Add ThetaJC to Thermal Impedance table. Fix package order number. Add CY logo. Update CY copyright.	
*G	352736	HMT	See ECN	Add new color and logo. Add URL to preferred dimensions for mounting packages. Update Transmitter and Receiver AC Digital Block Electrical fications.	
*H	390152	HMT	See ECN	Clarify MLF thermal pad connection info. Replace 16-Pin 300-MIL SOIC with correct 150-MIL.	
*	413404	HMT	See ECN	Update 32-Pin QFN E-Pad dimensions and rev. *A. Update CY branding and QFN convention.	
*J	430185	HMT	See ECN	Add new 32-Pin 5x5 mm 0.60 thickness QFN package and diagram, CY8C21434-24LKXI. Update thermal resistance data. Add 56-Pin SSOP on-chip debug non-production part, CY8C21001-24PVXI. Update typical and recommended Storage Temperature per industrial specs. Update copyright and trademarks.	
*K	677717	HMT	See ECN	Add CapSense SNR requirement reference. Add new Dev. Tool section. Add CY8C20x34 to PSoC Device Characteristics table. Add Low Power Comparator (LPC) AC/DC electrical spec. tables. Update rev. of 32-Lead (5x5 mm 0.60 MAX) QFN package diagram.	
*L	2147847	UVS / PYRS	02/27/08	Added 32-Pin QFN Sawn pin diagram, package diagram, and ordering information.	
*M	2273246	UVS / AESA	04/01/08	Added 32 pin thin sawn package diagram.	
*N	2618124	OGNE / PYRS	12/09/08	Added Note in Ordering Information section. Changed title from PSoC Mixed-Signal Array to PSoC Programmable System-on-Chip	
*O	2684145	SNV / AESA	04/06/2009	Updated 32-Pin Sawn QFN package dimension for CY8C21434-24LTXI Updated Getting Started, Development Tools, and Designing with PSoC Designer Sections	
*P	2693024	DPT / PYRS	04/16/2009	Updated 32-Pin Sawn QFN package diagram	
*Q	2720594	BRW	06/22/09	Corrected ohm symbol and parenthesis in figure caption (Fig.25) Removed references to mixed-sginal array from the text. Updated Development Tools Selection section.	

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